

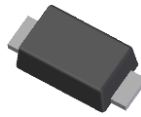
## Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **An automotive-compliant part is available under separate datasheet ([DFLS1150Q](#))**

## Mechanical Data

- Package: PowerDI<sup>®</sup>123
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 **Ⓔ3**
- Weight: 0.01 grams (Approximate)

PowerDI123



Top View

## Ordering Information (Note 4)

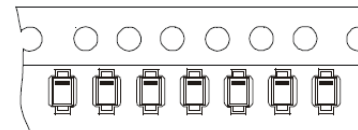
Part Number	Package	Packing	
		Qty.	Carrier
DFLS1150-7	PowerDI123	3,000	Tape & Reel
DFLS1150-13	PowerDI123	10,000	Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



F07 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: K = 2023)  
 M = Month (ex: 9 = September)



### Date Code Key

Year	2005	-	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	S	-	K	L	M	N	P	R	S	T	U	V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	150	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	106	V
Average Forward Current	I <sub>F(AV)</sub>	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine Wave Superimposed on Rated Load	I <sub>FSM</sub>	50	A

**Thermal Characteristics**

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point (Note 5)	R <sub>θJS</sub>	—	7	°C/W
Thermal Resistance Junction to Ambient (Note 6) T <sub>A</sub> = +25°C	R <sub>θJA</sub>	125	—	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175		°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	150	—	—	V	I <sub>R</sub> = 2μA
Forward Voltage	V <sub>F</sub>	—	—	0.82	V	I <sub>F</sub> = 1.0A
Leakage Current (Note 7)	I <sub>R</sub>	—	—	2	μA	V <sub>R</sub> = 150V, T <sub>A</sub> = +25°C
Total Capacitance	C <sub>T</sub>	—	28	—	pF	V <sub>R</sub> = 5V <sub>DC</sub> , f = 1MHz

- Notes:
5. Theoretical R<sub>θJS</sub> calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
  6. Part mounted on FR-4 board with 2 oz., minimum recommended copper pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
  7. Short duration pulse test used to minimize self-heating effect.

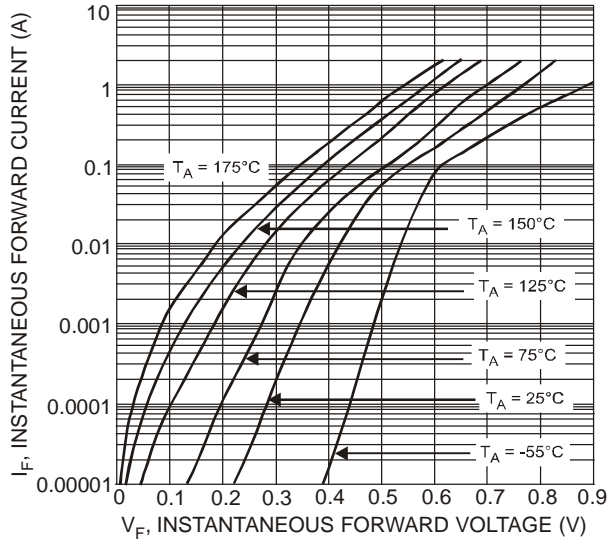


Fig. 1 Typical Forward Characteristics

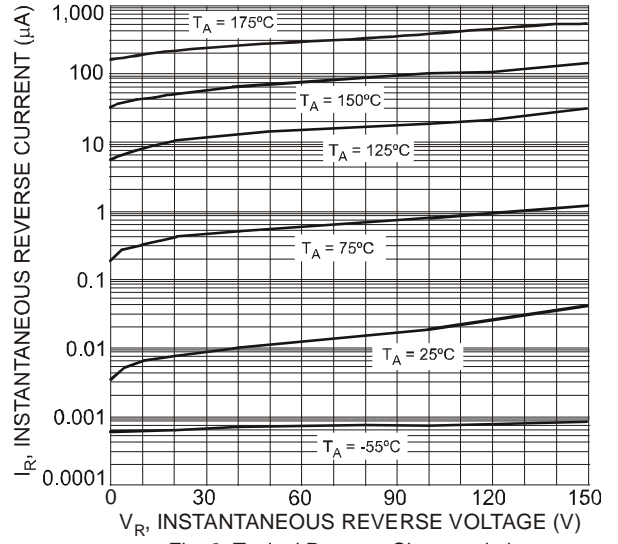


Fig. 2 Typical Reverse Characteristics

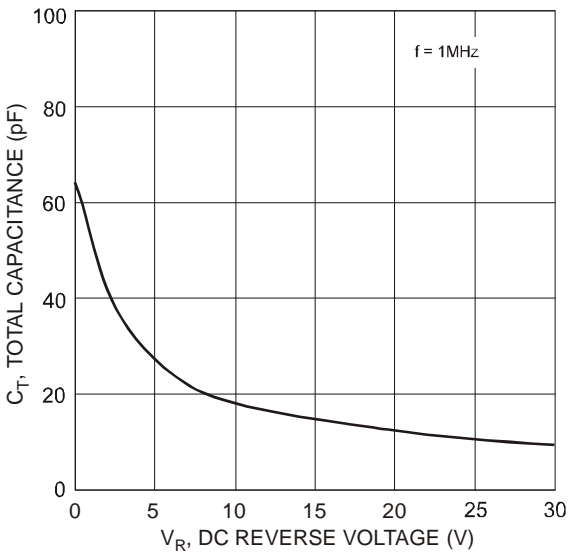
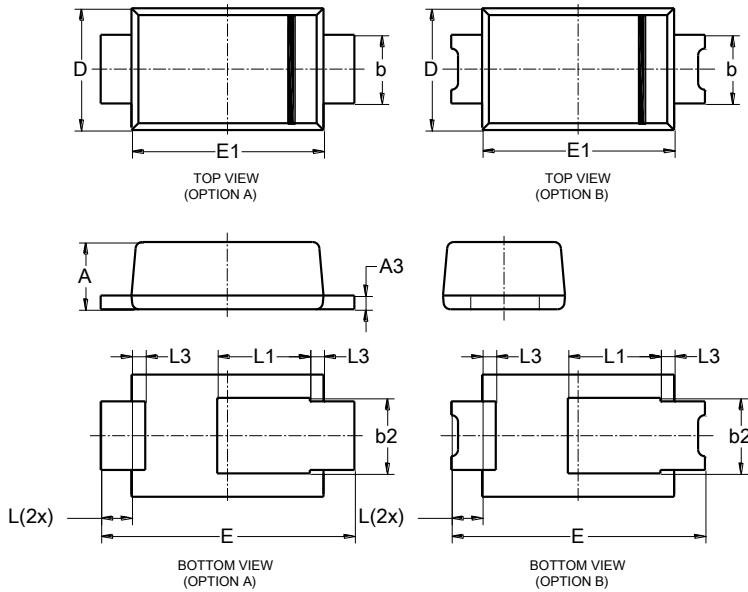


Fig. 3 Total Capacitance vs. Reverse Voltage

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI123**

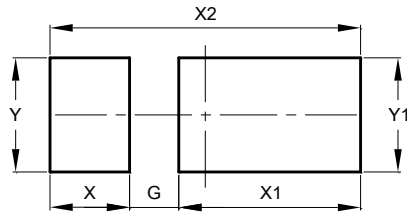


PowerDI123			
Dim	Min	Max	Typ
A	0.93	1.00	0.98
A3	0.15	0.25	0.20
b	0.85	1.25	1.00
b2	1.025	1.125	1.10
D	1.63	1.93	1.78
E	3.50	3.90	3.70
E1	2.60	3.00	2.80
L	0.40	0.50	0.45
L1	1.25	1.40	1.35
L3	0.125	0.275	0.20
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI123**



Dimensions	Value (in mm)
G	0.65
X	1.05
X1	2.40
X2	4.10
Y	1.50
Y1	1.50

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